3mm Round Bi-Colour LED
Red/Green

multicomp PRO

Features

- Choice of various viewing angles
- Available on tape and reel
- Reliable and robust
- Lead Free

Specifications

Dice material : GaAsP / GaAsP
Emmiting Colour : Red / Green
Lens colour : White Diffused
Dominant wavelength : 630nm / 575nm
Luminous intensity (IV) : 10mcd / 14mcd

RoHS Compliant

Applications

- TV set
- Monitor
- Telephone
- Computer

Selection Guide

Part Number	Dice	Lens Type	Luminous intensity(mcd) @ 20mA			Viewing Angle
			Min	Typ	Max	2θ1/2
MP008274	(R)GaAsP	White Diffused	4	10	-	60
	(B)GaAsP		6	14	-	

Note:
1. 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. The above luminous intensity measurement allowance tolerance ±15%

Electrical and Optical Characteristics at Ta=25°C

Parameter	Device	Min.	Typ	Max	Units	Test conditions
Forward voltage	R	1.7	2	2.4	V	IF=20mA
	G	1.7	2	2.4		
Reverse Current	IR	-	-	10	uA	VR=5V
Dominant wavelength	R	620	-	630	nm	IF=20mA
	G	565	-	575		

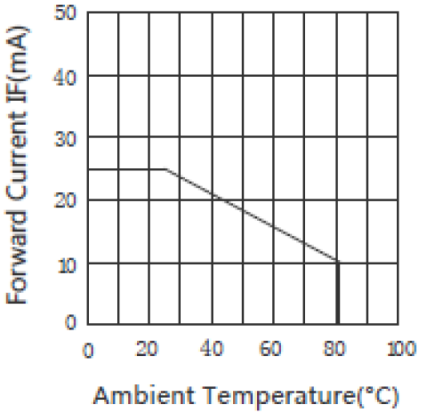
Absolute Maximum Ratings at Ta=25°C

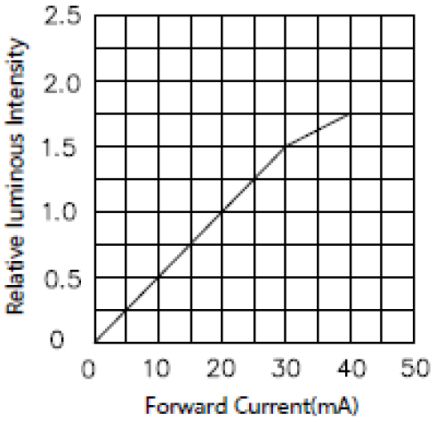
Parameter	Symbol	Rating	Units
Power Dissipation	R	60	mW
DC Forward Current	IF	30	mA
Peak Forward Current [1]	IFP	60	
Reverse Voltage	VR	5	V
Electrostatic Discharge (HBM)	ESD	2000	V
Operating Temperature	Topr	-40 to +85	°C
Storage Temperature	Tstg	-40 to +100	
Lead Soldering Temperature [1.6mm(.063”) From Body]		260°C for 5 seconds	

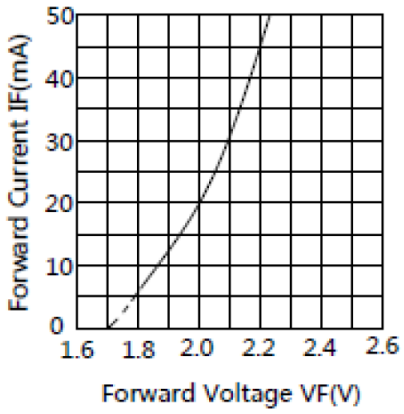
Notes:
1. 1/10 Duty cycle,0.1ms pulse width.
2. Measurement Errors:Forward Voltage:±0.1V,Luminous Intensity:±10%mcd,Wavelength(x,y)±1nm/±0.01

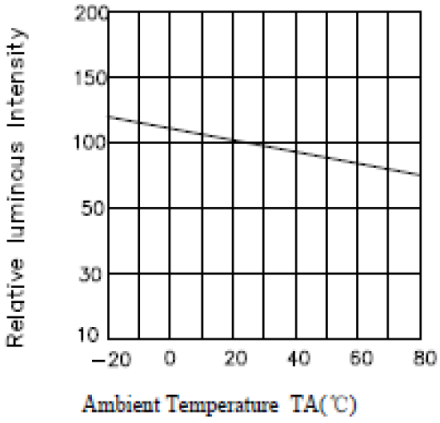
Typical optical characteristics curves

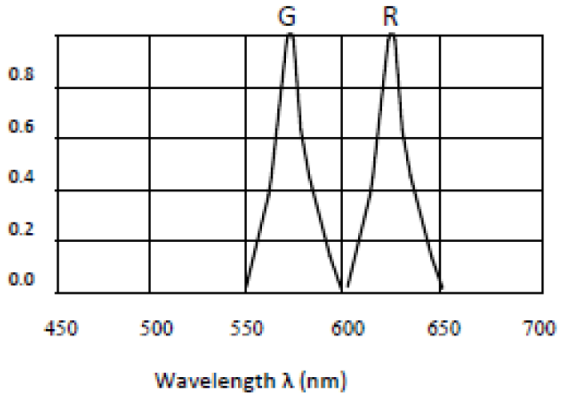
Ambient Temperature VS. Forward Current

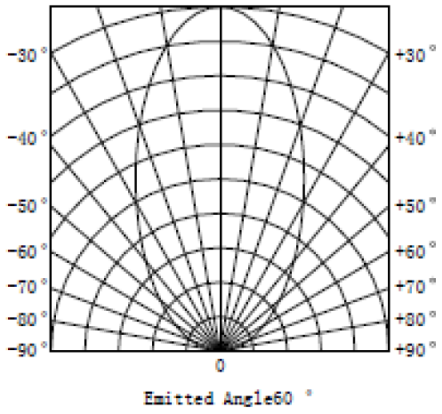




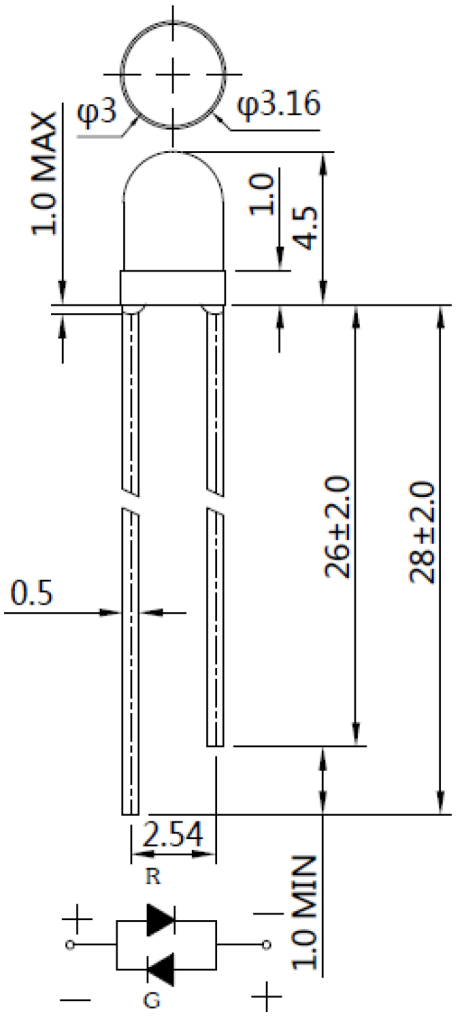








Dimensions



Tolerance is ±0.25mm unless otherwise noted.

Dimensions : Millimetres

1. Soldering

- When soldering leave a minimum of 2mm clearance from the base of the lens to the soldering point.
- Dipping the lens into the solder must be avoided.
- Do not apply any external stress to the lead frame during soldering while the LED is at high temperature.

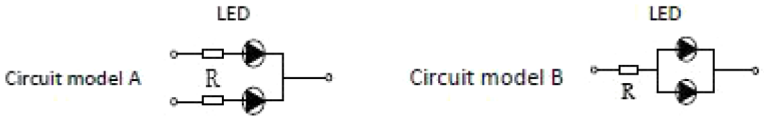
Recommended soldering conditions:

Soldering iron		Wave soldering	
Temperature	320°C Max	Pre-heat Pre-heat time	120°C Max 120 sec.Max
Soldering time	3 sec.Max (one time only)	Solder wave Soldering time	260°C Max 5 sec.Max

Note: Excessive soldering temperature and/or time might result in deformation of the LED lens or catastrophic failure of the LED.

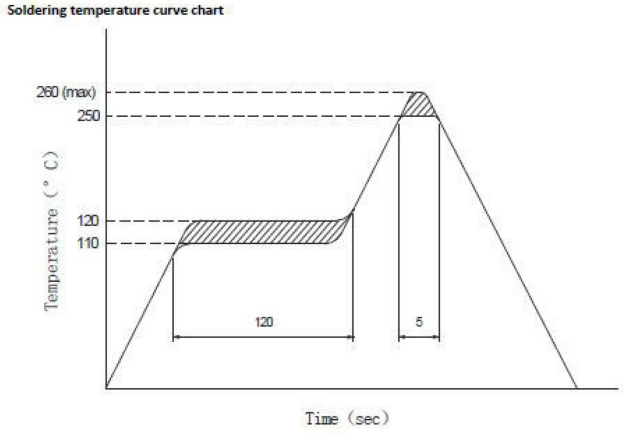
2. Drive Method

An LED is a current-operated device,In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application,it is recommended that a current limiting resistor be incorporated in the drive circuit,in series with each LED as shown in Circuit A below.



(A) Recommended circuit

(B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.



NOTES

After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature. A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.

Part Number Table

Description	Part Number
Round LED, Red/Geen, 630/575nm, 60°, 10/14mcd, Through hole	MP008274